



## Features:

- For Surface Mounted Applications
- Low Profile Package
- Built-In Strain Relief
- Metal Silicon Junction, Majority Carrier Conduction
- High Surge Capability
- Low Power Loss, High Efficiency
- For Use In Low Voltage High Frequency Inverters, Free Wheeling And Polarity Protection Applications
- Guard Ring For Over Voltage Protection
- High Temperature Soldering Guaranteed : 250°C/10 Seconds At Terminals

## Mechanical Data

- Case: JEDEC SMB, molded plastic over passivated chip
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Colour band denotes cathode end
- Weight: 0.003oz, 0.093g

## Maximum Ratings and Thermal Characteristics

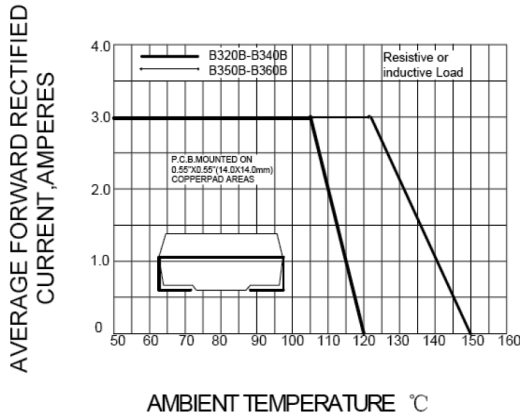
Ratings at 25°C ambient temperature unless otherwise specified

Characteristic	Symbol	B330B-13-F	B340B-13-F	B360B-13-F	Units
Maximum repetitive peak reverse voltage	$V_{RRM}$	30	40	60	V
Maximum RMS voltage	$V_{RWS}$	21	28	42	V
Maximum DC blocking voltage	$V_{DC}$	30	40	50	V
Maximum average forward rectified current at $T_L$ =See Fig. 2 (Note 2)	$I_{F(AV)}$	3			A
Peak forward surge current 8.3ms single half-sine-wave	$I_{FSM}$	50			A
Maximum instantaneous forward voltage at 3A (Note 1)	$V_F$	0.5		0.7	V
Maximum DC reverse current at $T_A = 25^\circ\text{C}$ at rated DC blocking voltage at $T_A = 100^\circ\text{C}$ (Note 1)	$I_R$	0.5 20			mA
Typical thermal resistance (Note 2)	$R_{\theta JA}$ $R_{\theta JL}$	50 20			$^\circ\text{C/W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +125			$^\circ\text{C}$

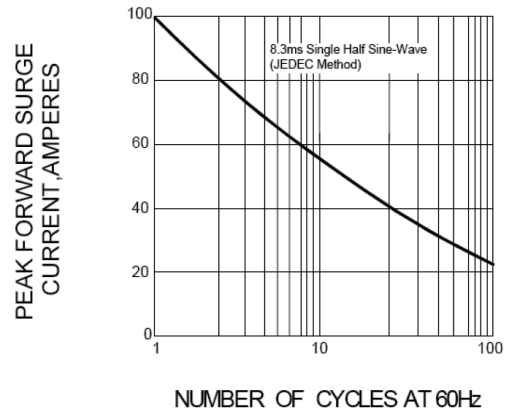
### Notes:

- (1) Pulse test: 300 $\mu\text{s}$  pulse width, 1% duty cycle.
- (2) PCB mounted with 0.55"  $\times$  0.55" (14  $\times$  14mm<sup>2</sup>) copper pad areas.

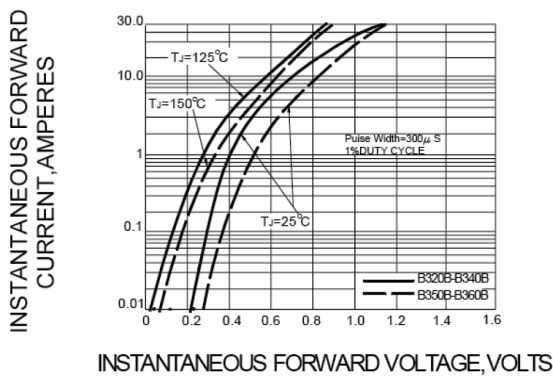
**FIG.1 – FORWARD DERATING CURVE**



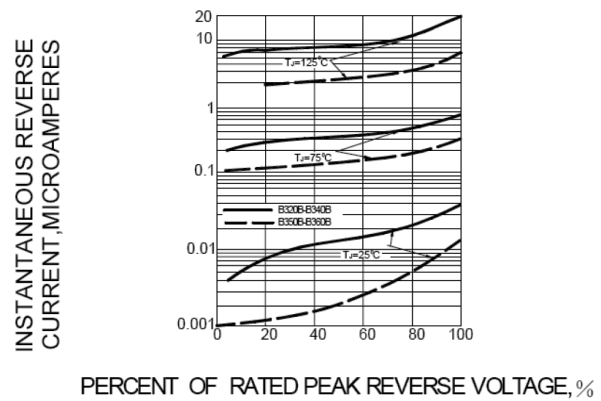
**FIG.2– PEAK FORWARD SURGE CURRENT**



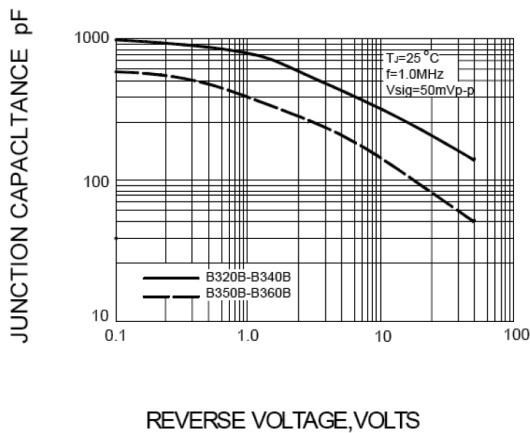
**FIG.3 – TYPICAL FORWARD CHARACTERISTICS**



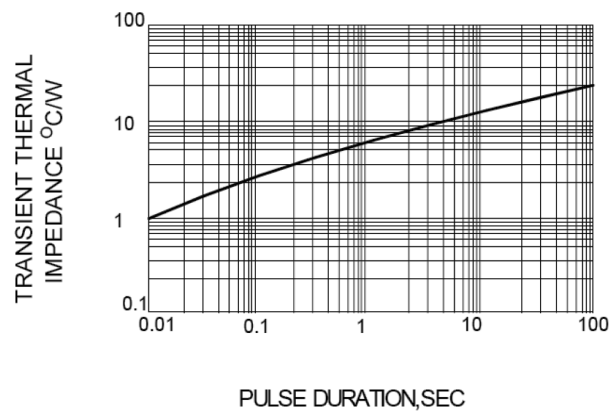
**FIG.4 – TYPICAL REVERSE CHARACTERISTICS**



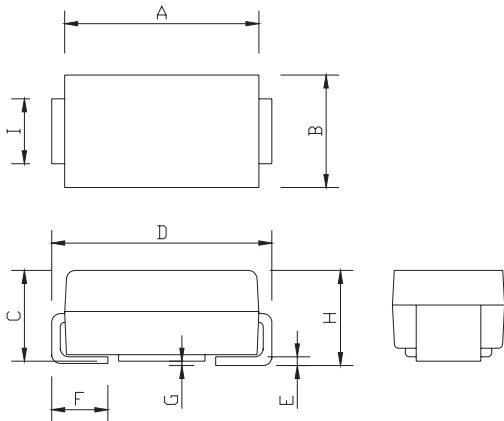
**FIG.5-TYPICAL JUNCTION CAPACITANCE**



**FIG.6- TYPICAL TRANSIENT THERMAL IMPEDANCE**



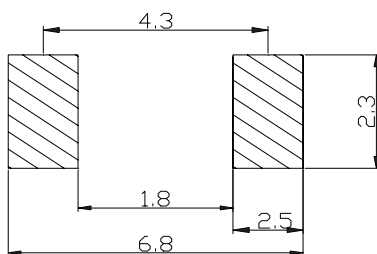
## Package Outline Dimensions



SMB		
Dim.	Min.	Max.
A	4.3	4.7
B	3.3	3.7
C	2	2.3
D	5.05	5.55
E	0.2 Typ.	
F	0.95	1.55
G	0.2 Max.	
H	2.1	2.5
I	1.85	2.15

Dimensions : Millimetres

## Soldering Footprint



Dimensions : Millimetres

## Package Information

Device	Package	Shipping
B330B -13-F B340B -13-F B360B -13-F	DO-214AA(SMB)	3,000 / Tape & Reel

## Part Number Table

Description	Part Number
Schottky Barrier Rectifier	B330B-13-F
	B340B-13-F
	B360B-13-F

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